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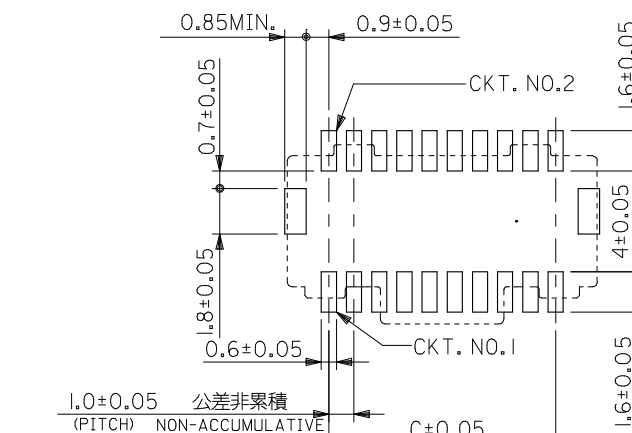
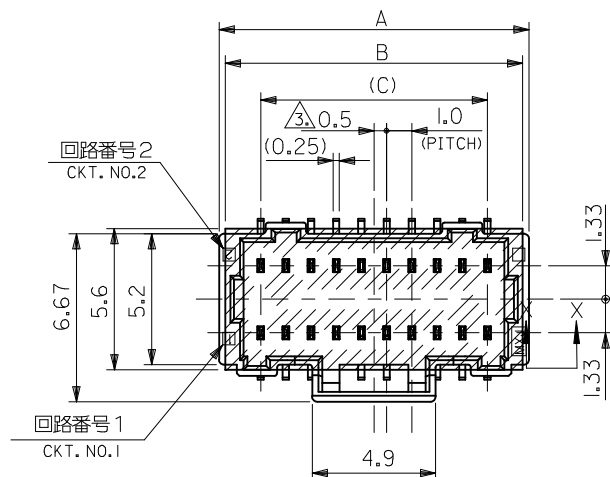
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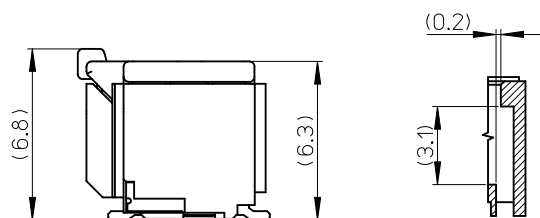
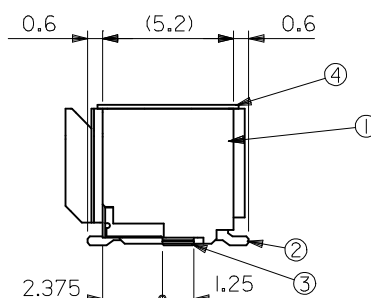
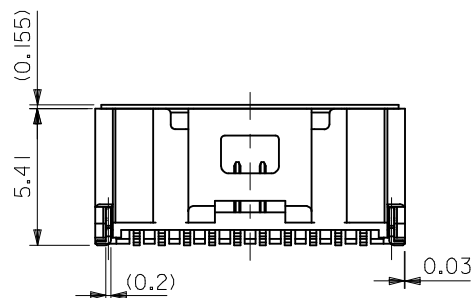
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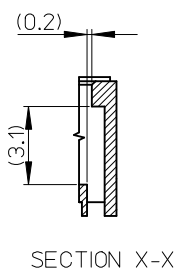
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参考パターンレイアウト
RECOMMENDED PATTERN DIM. (REF.)



嵌合高さ
MATING HEIGHT



SECTION X-X

番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン, UL94V-0, 色: シート2参照 HEAT RESISTANCE NYLON, UL94V-0, COLOR: SEE SHEET 2
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ: 0.1 μmMIN. GOLD ニッケルメッキ (下地): 1.0 μmMIN. NICKEL (UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0 μmMIN. TIN ニッケルメッキ (下地): 1.0 μmMIN. NICKEL (UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

- 嵌合相手: 501189-****
MATE WITH: 501189-****
- ソルダーピン及びネイル平坦度は、0.1 MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- 極数/2=偶数に適用
APPLY FOR CKT SIZE/2=EVEN
- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

無 NO	24		27.3	501190-5027	501190-5029	50
	19		22.3	501190-4027	501190-4029	40
	14		17.3	501190-3027	501190-3029	30
	9		12.3	501190-2027	501190-2029	20
有 YES	24	26.8	27.3	501190-5017	501190-5019	50
	19	21.8	22.3	501190-4017	501190-4019	40
				501190-405*	501190-407*	
	14	16.8	17.3	501190-3017	501190-3019	30
				501190-305*	501190-307*	
	9	11.8	12.3	501190-2017	501190-2019	20
				501190-205*	501190-207*	
	カバーテープの有無 COVER TAPE	C	B	A	EMBOSSED PACKAGE	CONNECTOR
オーダー番号 ORDER NO.					SERIES NO.	

REVISED EC NO: J2014-1175 DRAWN: HORI CHKD: KASAKAWA APPR: NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2004/12/17	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2004/12/17					
		30 OVER	± 0.3	APPROVED BY ANODA	DATE 2004/12/17					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-501190-003				1 OF 2
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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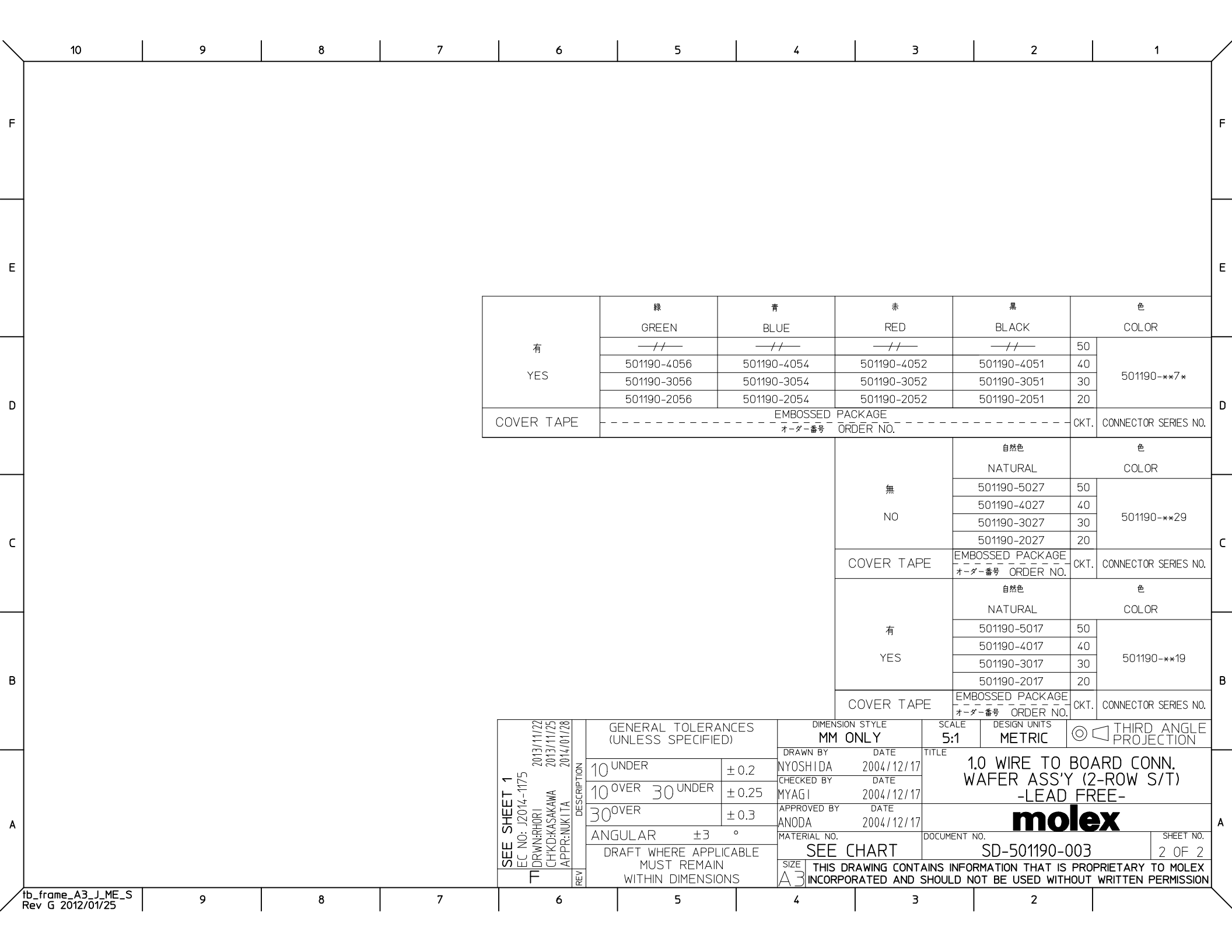
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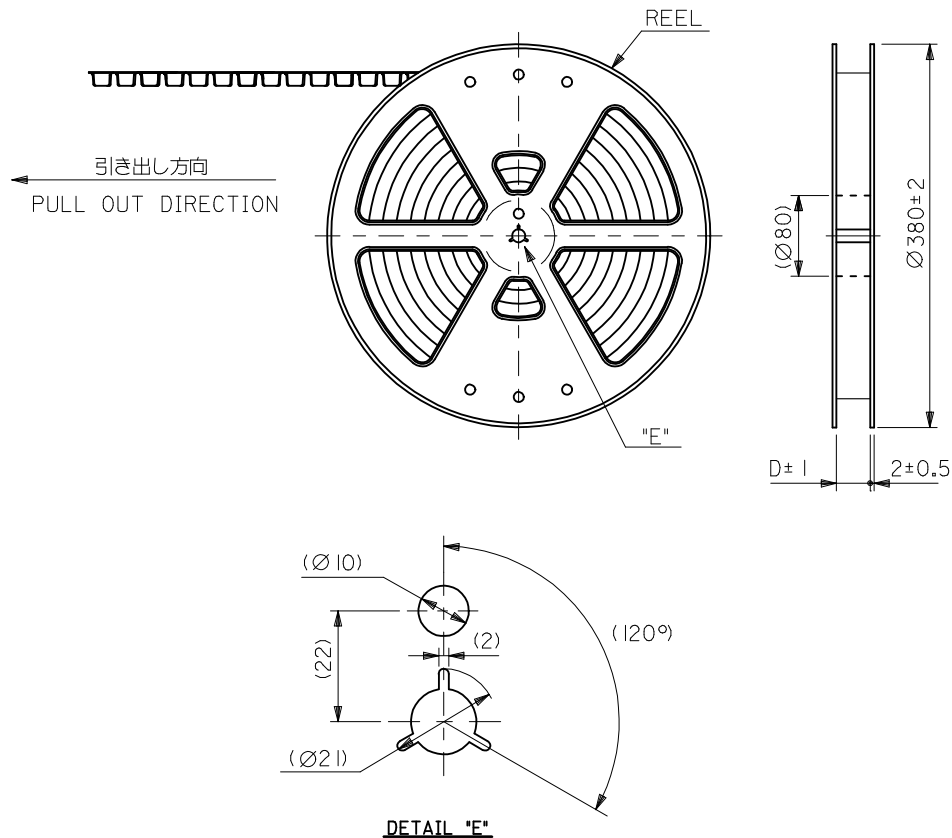
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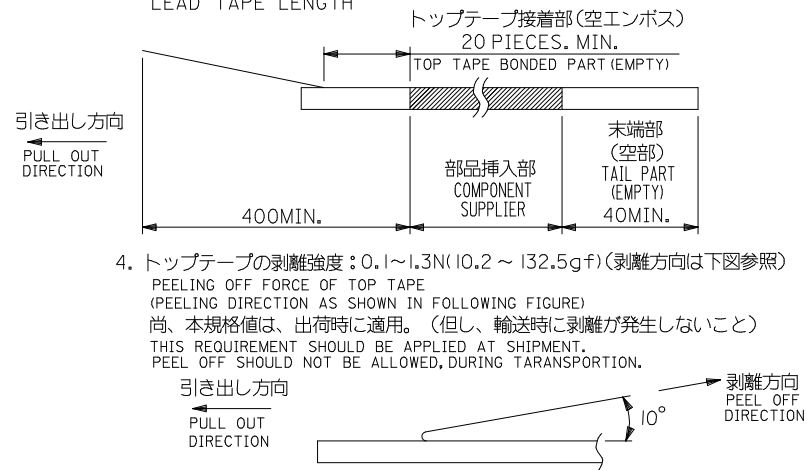


NOTES

1. 製品詳細寸法については SD-501190-003 を参照ください。
RE DETAILED DIMENSION, SEE SD-501190-003

2. 梱包数量：1100個/リール
NUMBER OF CONNECTORS：1100PIECES/REEL

3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度：0.1～1.3N(10.2～132.5gf)(剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しないこと)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.

5. 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ：PET, PE, REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL: POLYSTYRENE (RECYCLE MATERIAL CONTAINED)

6. 乾燥剤入り防湿梱包仕様になります。(501190-**17, 501190-**27以外)
INCLUDING DESICCANT TAPING PACKAGE.
(BESIDES 501190-**17, 501190-**27)

7. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

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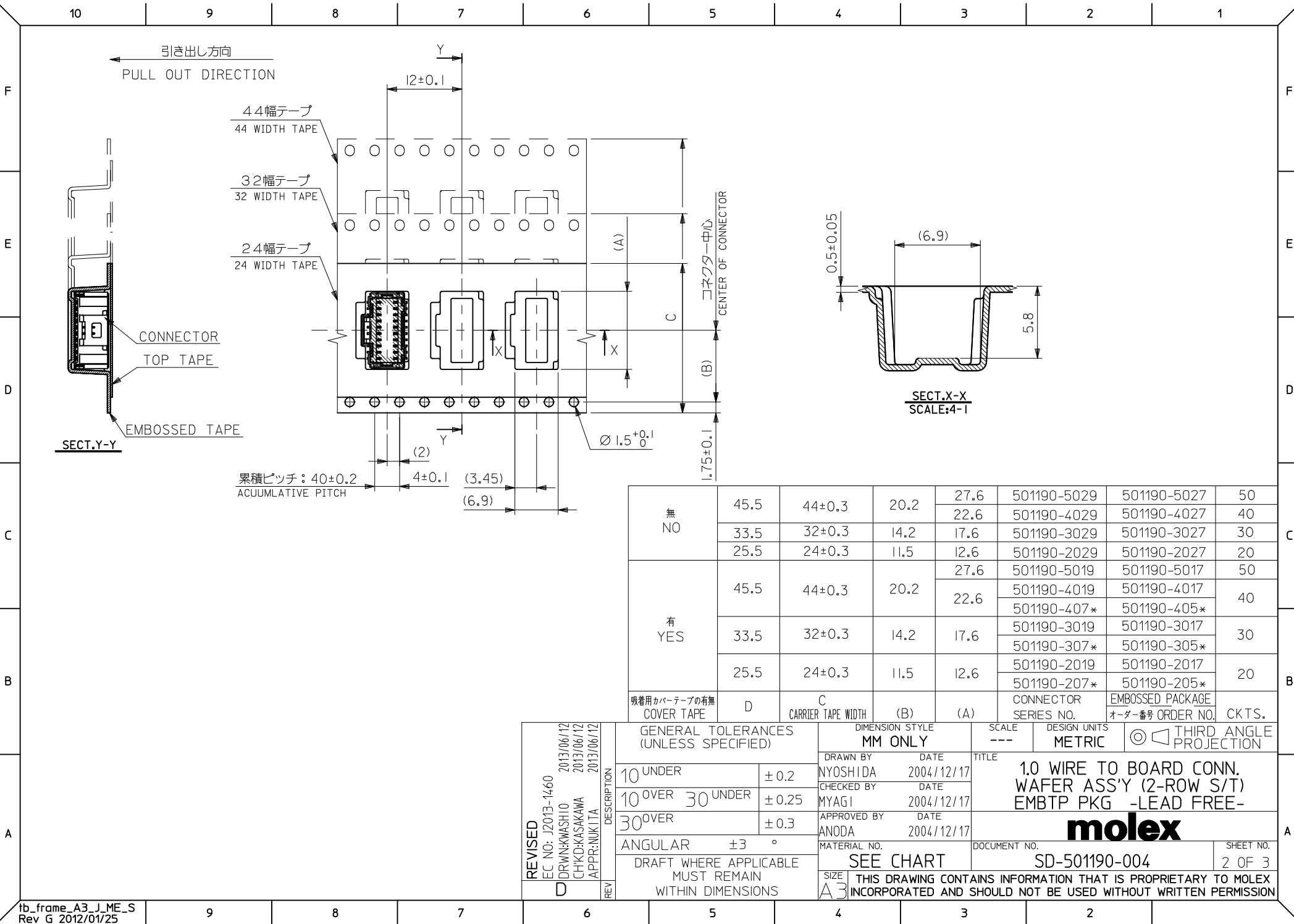
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REVISED EC NO.: J2013-1460 DRW: KAWASHIO CHKD: KASAKAWA APPR: NUKITA REV	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
				MM ONLY		---	METRIC				
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (2-ROW S/T) EMBTP PKG -LEAD FREE-					
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE						
		30 OVER	± 0.3	APPROVED BY	DATE						
	ANGULAR ±3 °		ANODA		molex						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.								
D	REV			SIZE A3		SEE SHEET 2		DOCUMENT NO. SD-501190-004		SHEET NO. 1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											



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Rev G 2012/01/25